

Features

- 1210 1.1mm SMD LED
- High Brightness
- AlInGaP / InGaN Technology
- Side View
- High reliability
- Clear Lens

Applications

- Consumer Electronics
- Wearables
- Automobile After Market
- Industrial Equipment

Description

The IN-S128TATRGB is a popular 1210 top view RGB package with versatile design capabilities. It is a PCB type molding style LED which can be used in various applications.

Recommended Solder Pattern

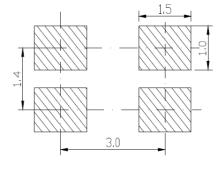
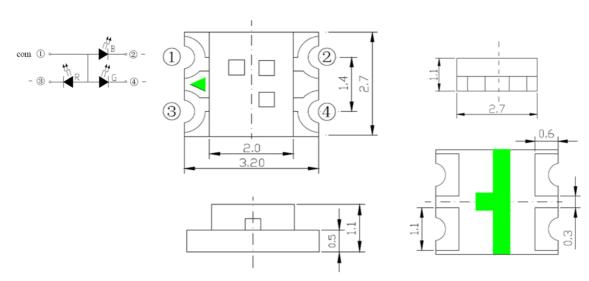


Figure 1. IN-S128TATRGB Solder Pattern



Package Dimensions in mm

Notes.

- 1. All dimensions are in millimeters.
- 2. Tolerance is ± 0.10 mm unless otherwise noted





Absolute Maximum Rating at 25°C (Note 1)

Product	Emission Color	P _d (mW)	I _F (mA)	I _{FP} * (mA)	V _R (V)	T _{OP} (°C)	T _{st} (°C)		
	Red	75	25	60					
IN-S128TATRGB	Green	75	25	100	5	-30~+85	-40~+90		
	Blue	75	25	100					

Notes

1. Condition for IFP is pulse of 1/10 duty and 0.1msec width

ESD Precaution

ATTENTION: Electrostatic Discharge (ESD) protection

The symbol above denotes that ESD precaution is needed. ESD protection for GaP and AlGaAs based chips is necessary even though they are relatively safe in the presence of low static-electric discharge. Parts built with AlInGaP, GaN, or/and InGaN based chips are STATIC SENSITIVE devices. ESD precaution must be taken during design and assembly. If manual work or processing is needed, please ensure the device is adequately protected from ESD during the process.

Please be advised that normal static precautions should be taken in the handling and assembly of this device to prevent damage or degradation which may be induced by electrostatic discharge (ESD).

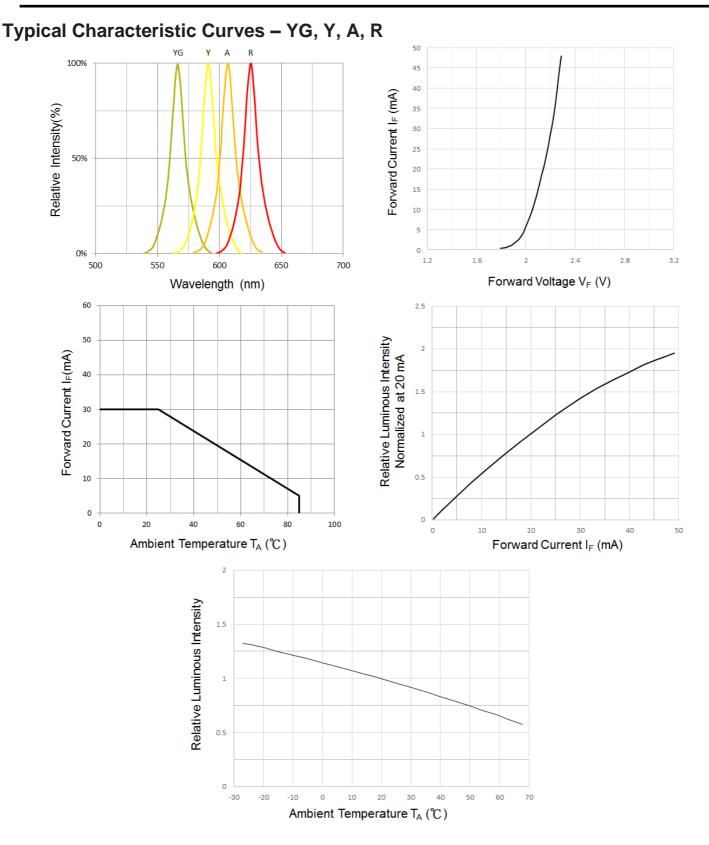
Electrical Characteristics $T_A = 25^{\circ}$ (Note 1)

Product	Emission Color	l⊧ (mA)	V	=(V)	λ(nm)			Viewing Angle	I [*] ∨(mcd)	
			typ.	max	λ_{D}	λ_{P}	$ riangle \lambda$	201/2	Min.	Max
	Red	20	2.2	2.6	625	636	20	130	150	200
IN-S128TATRGB	Green	20	3.2	3.6	520	521	35	130	210	600
	Blue	20	3.2	3.6	465	464	30	130	125	180

Notes

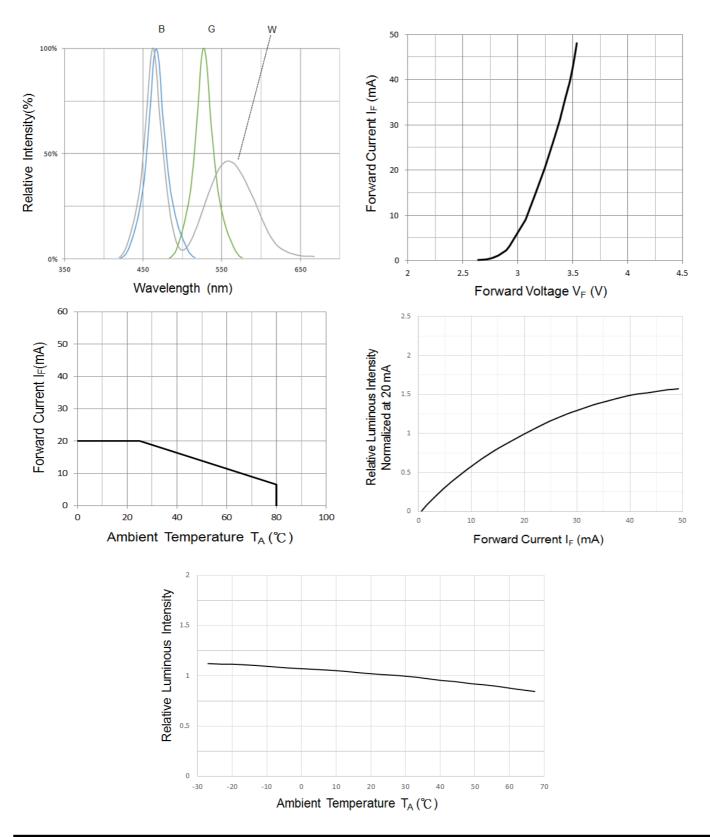
1. Performance guaranteed only under conditions listed in above tables.





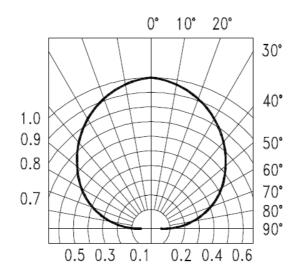








Typical Characteristic Curves – Radiation Pattern

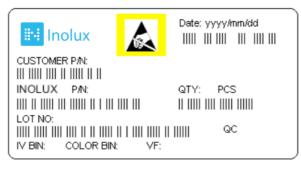


Ordering Information

Product	Emission Color	Technology	Test Current I _F (mA)	Luminous Intensity Iv (mcd) (Typ.)	Forward Voltage V _F (V) (Typ.)	Orderable Part Number
	Red	AllnGaP	20	200	2.2	
IN-S128TATRGB	Green	InGaN	20	600	3.2	IN-S128TATRGB
	Blue	InGaN	20	180	3.2	



Label Specifications



Inolux P/N:

I	Ν	-	S	1	2	8	Т	А	Т			R	G	В	-	-	-	-	-
			Material	F	Package	9	Var	iation	Orientation	rientation Current Lens		Color						nizec p-off	
	slux ИD		S = PCB Type	128	TA = 3. T	2 x 2.7 ri-Chip		mm	T = Top Mount	(Blank) = 20mA	(Blank) = Clear	G	=636n =521n =464n	m			-		

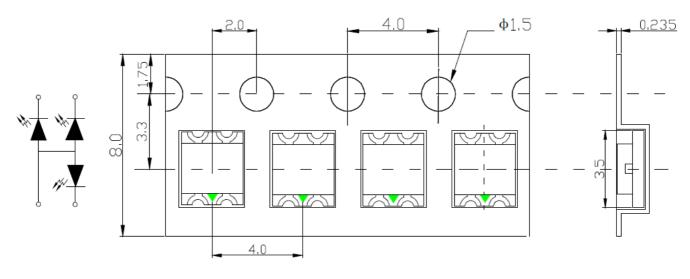
Lot No.:

Z	2	0	1	7	01	24	001
Internal		Voar (2017	, 2018,)	Month	Date	Serial	
Tracker		1601 (2017	, 2010,)	wonth	Date	Serial	



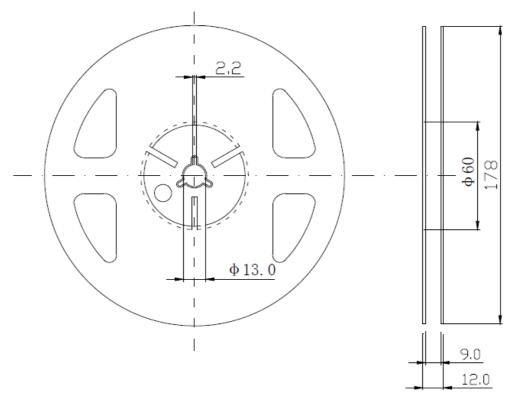
Packaging Information: 3000pcs Per Reel

Tape Dimension



Unit: mm Tolerance: +/-0.10 mm

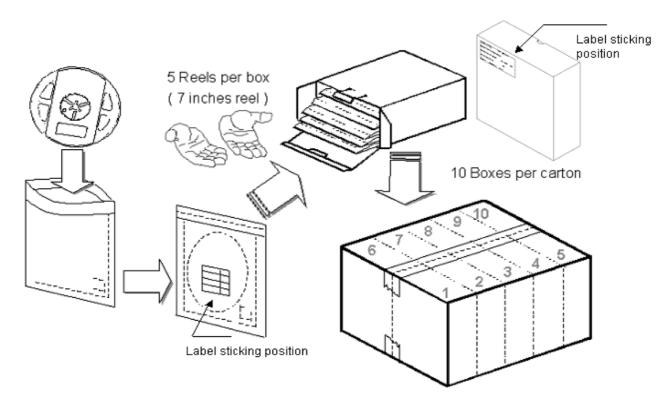
Reel Dimension







Packing Dimension



5 boxes per carton are available depending on shipment quantity.

Specification	Material	Quantity
Per EIA 481-1A specs	Conductive black tape	3000pcs per reel
Per EIA 481-1A specs	Conductive black	
IN standard	Paper	
220x240mm	Aluminum laminated bag/ no-zipper	One reel per bag
IN standard	Paper	Non-specified
-	Per EIA 481-1A specs Per EIA 481-1A specs IN standard 220x240mm	Per EIA 481-1A specs Conductive black tape Per EIA 481-1A specs Conductive black IN standard Paper 220x240mm Aluminum laminated bag/ no-zipper

Others:

Each immediate box consists of 5 reels. The 5 reels may not necessarily have the same lot number or the same bin combinations of Iv, λ_D and Vf. Each reel has a label identifying its specification; the immediate box consists of a product label as well.

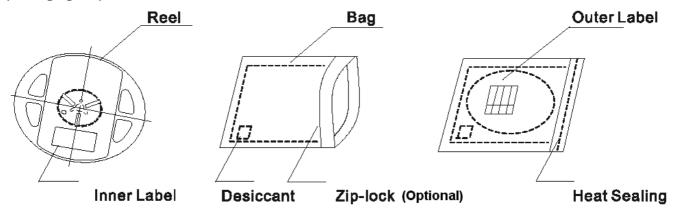


Dry Pack

All SMD optical devices are **MOISTURE SENSITIVE**. Avoid exposure to moisture at all times during transportation or storage. Every reel is packaged in a moisture protected anti-static bag. Each bag is properly sealed prior to shipment.

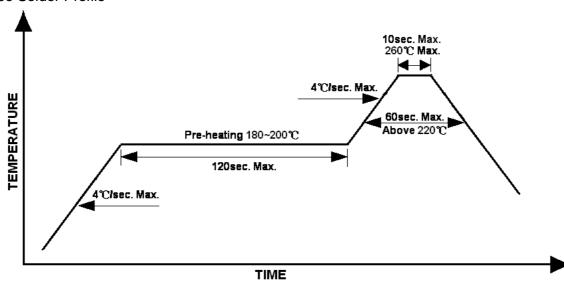
Upon request, a humidity indicator will be included in the moisture protected anti-static bag prior to shipment.

The packaging sequence is as follows:



Reflow Soldering

- Recommended tin glue specifications: melting temperature in the range of 178~192 °C
- The recommended reflow soldering profile is as follows (temperatures indicated are as measured on the surface of the LED resin):



Lead-free Solder Profile



Precautions

- Avoid exposure to moisture at all times during transportation or storage.
- Anti-Static precaution must be taken when handling GaN, InGaN, and AllnGaP products.
- It is suggested to connect the unit with a current limiting resistor of the proper size. Avoid applying a reverse voltage.
- Avoid operation beyond the limits as specified by the absolute maximum ratings.
- Avoid direct contact with the surface through which the LED emits light.
- If possible, assemble the unit in a clean room or dust-free environment.

Reworking

- Rework should be completed within 5 seconds under 260 °C.
- The iron tip must not come in contact with the copper foil.
- Twin-head type is preferred.

Cleaning

Following are cleaning procedures after soldering:

- An alcohol-based solvent such as isopropyl alcohol (IPA) is recommended.
- Temperature x Time should be 50°C x 30sec. or <30°C x 3min
- Ultra sonic cleaning: < 15W/ bath; bath volume ≤ 1liter
- Curing: 100 °C max, <3min

Cautions of Pick and Place

- Avoid stress on the resin at elevated temperature.
- Avoid rubbing or scraping the resin by any object.
- Electro-static may cause damage to the component. Please ensure that the equipment is properly grounded. Use of an ionizer fan is recommended.



Reliability

Item	Frequency/ lots/ samples/	Standards	Conditions				
nem	failures	Reference					
	For all reliability	J-STD-020	1.) Baking at 85°C for 24hrs				
Precondition	monitoring tests according		2.) Moisture storage at 85°C/ 60% R.H. for				
	to JEDEC Level 2		168hrs				
	1Q/ 1/ 22/ 0	JESD22-B102-B	Accelerated aging 155°C/ 24hrs				
Solderability		And CNS-5068	Tinning speed: 2.5+0.5cm/s				
			Tinning: A: 215°C/ 3+1s or B: 260°C/ 10+1s				
		CNS-5067	Dipping soldering terminal only				
Resistance to			Soldering bath temperature				
soldering heat			A: 260+/-5°C; 10+/-1s				
		.	B: 350+/-10°C; 3+/-0.5s				
	1Q/ 1/ 40/ 0	CNS-11829	1.) Precondition: 85°C baking for 24hrs				
Operating life test			85°C/ 60%R.H. for 168hrs				
	10/1/15/0		2.) Tamb25°C; IF=20mA; duration 1000hrs				
High humidity,	1Q/ 1/ 45/ 0	JESD-A101-B	Tamb: 85°C				
high temperature			Humidity: 85% R.H., IF=5mA				
bias	40/4/00	IN 1	Duration: 1000hrs				
High temperature	1Q/ 1/ 20	IN specs.	Tamb: 55°C				
bias			IF=20mA				
	1Q/ 1/ 40/ 0		Duration: 1000hrs Tamb25°C, If=20mA,, Ip=100mA, Duty				
Pulse life test	10/1/40/0		cycle=0.125 (tp=125 μ s,T=1sec)				
Puise life test							
	1Q/ 1/ 76/ 0	JESD-A104-A	Duration 500hrs) A cycle: -40 degree C 15min; +85 degree C				
	10/1/76/0		15min 40 degree C T5min; +85 degree C				
Temperature		IEC 68-2-14, Nb					
cycle			Thermal steady within 5 min 300 cycles				
			2 chamber/ Air-to-air type				
High humidity	1Q/ 1/ 40/ 0	CNS-6117	60+3°C				
storage test			90+5 C 90+5/-10% R.H. for 500hrs				
High temperature	1Q/ 1/ 40/ 0	CNS-554	100+10°C for 500hrs				
storage test		0110-004					
Low temperature	1Q/ 1/ 40/ 0	CNS-6118	-40+5°C for 500hrs				
storage test							
sionage lesi		1					



Revision History

Changes since last revision	Page	Version No.	Revision Date
Initial Release		1.0	05-12-2017
Updated	1	1.1	08-29-2023

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